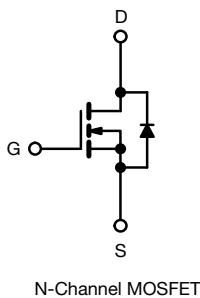
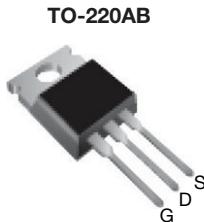


## Power MOSFET

<b>PRODUCT SUMMARY</b>	
V <sub>DS</sub> (V)	200
R <sub>DS(on)</sub> ( $\Omega$ )	V <sub>GS</sub> = 5.0 V    0.18
Q <sub>g</sub> max. (nC)	66
Q <sub>gs</sub> (nC)	9.0
Q <sub>gd</sub> (nC)	38
Configuration	Single



### FEATURES

- Dynamic dv/dt rating
- Repetitive avalanche rated
- Logic-level gate drive
- R<sub>DS(on)</sub> specified at V<sub>GS</sub> = 4 V and 5 V
- Fast switching
- Ease of paralleling
- Simple drive requirements
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)


**RoHS\***  
Available

### Note

\* This datasheet provides information about parts that are RoHS-compliant and / or parts that are non-RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details.

### DESCRIPTION

Third generation power MOSFETs from Vishay provides the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost effectiveness.

The TO-220AB package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220AB contribute to its wide acceptance throughout the industry.

### ORDERING INFORMATION

Package	TO-220AB
Lead (Pb)-free	IRL640PbF SiHL640-E3
SnPb	IRL640 SiHL640

### ABSOLUTE MAXIMUM RATINGS (T<sub>C</sub> = 25 °C, unless otherwise noted)

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V <sub>DS</sub>	200	V
Gate-Source Voltage	V <sub>GS</sub>	± 10	
Continuous Drain Current	V <sub>GS</sub> at 5.0 V	T <sub>C</sub> = 25 °C	A
		T <sub>C</sub> = 100 °C	
Pulsed Drain Current <sup>a</sup>	I <sub>DM</sub>	68	
Linear Derating Factor		1.0	W/°C
Single Pulse Avalanche Energy <sup>b</sup>	E <sub>AS</sub>	580	mJ
Repetitive Avalanche Current <sup>a</sup>	I <sub>AR</sub>	10	A
Repetitive Avalanche Energy <sup>a</sup>	E <sub>AR</sub>	13	mJ
Maximum Power Dissipation	P <sub>D</sub>	125	W
Peak Diode Recovery dv/dt <sup>c</sup>	dv/dt	5.0	V/ns
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C
Soldering Recommendations (Peak temperature) <sup>d</sup>	for 10 s	300	
Mounting Torque	6-32 or M3 screw	10	lbf · in
		1.1	N · m

### Notes

a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).

b. V<sub>DD</sub> = 50 V, starting T<sub>J</sub> = 25 °C, L = 3.0 mH, R<sub>g</sub> = 25 Ω I<sub>AS</sub> = 17 A (see fig. 12).

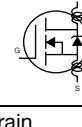
c. I<sub>SD</sub> ≤ 17 A, dI/dt ≤ 150 A/ms, V<sub>DD</sub> ≤ V<sub>DS</sub>, T<sub>J</sub> ≤ 150 °C.

d. 1.6 mm from case.

**THERMAL RESISTANCE RATINGS**

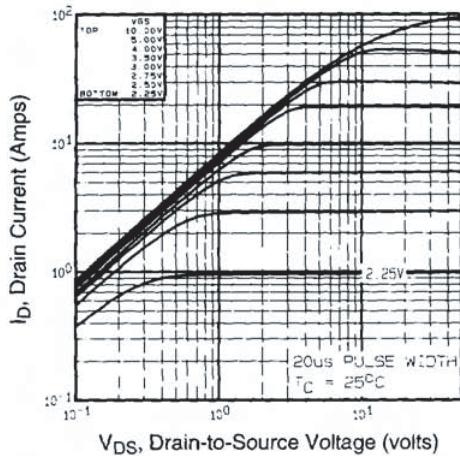
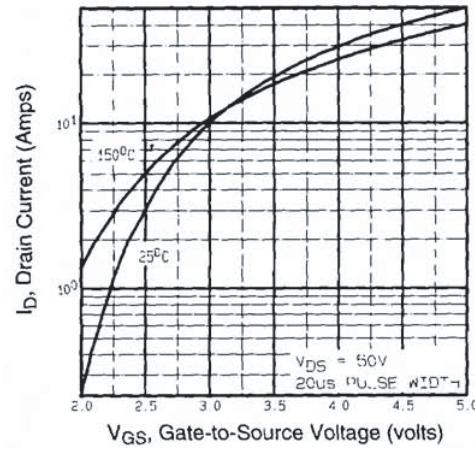
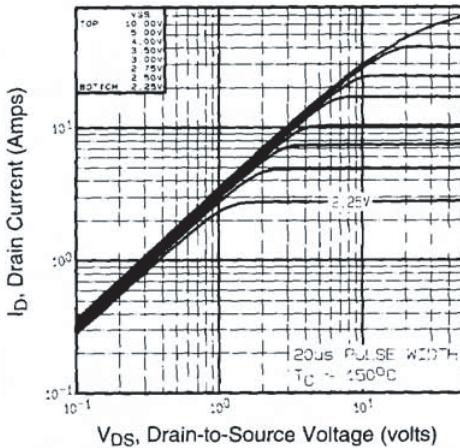
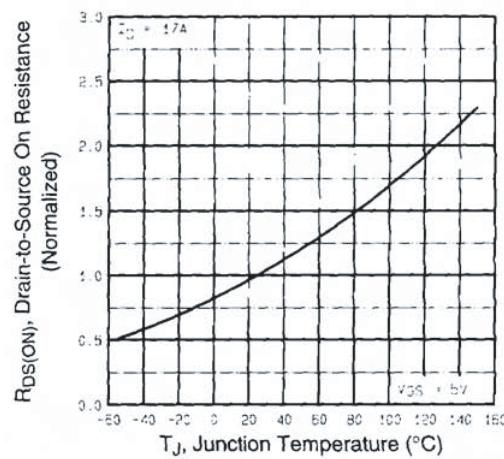
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	$R_{thJA}$	-	62	$^{\circ}\text{C}/\text{W}$
Case-to-Sink, Flat, Greased Surface	$R_{thCS}$	0.50	-	
Maximum Junction-to-Case (Drain)	$R_{thJC}$	-	1.0	

**SPECIFICATIONS** ( $T_J = 25 \text{ }^{\circ}\text{C}$ , unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
<b>Static</b>							
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0 \text{ V}$ , $I_D = 250 \mu\text{A}$		200	-	-	V
$V_{DS}$ Temperature Coefficient	$\Delta V_{DS}/T_J$	Reference to $25 \text{ }^{\circ}\text{C}$ , $I_D = 1 \text{ mA}$		-	0.27	-	$\text{V}/\text{ }^{\circ}\text{C}$
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$ , $I_D = 250 \mu\text{A}$		1.0	-	2.0	V
Gate-Source Leakage	$I_{GSS}$	$V_{GS} = \pm 10$		-	-	$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 200 \text{ V}$ , $V_{GS} = 0 \text{ V}$		-	-	25	$\mu\text{A}$
		$V_{DS} = 160 \text{ V}$ , $V_{GS} = 0 \text{ V}$ , $T_J = 125 \text{ }^{\circ}\text{C}$		-	-	250	
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS} = 5.0 \text{ V}$	$I_D = 10 \text{ A}^b$	-	-	0.18	$\Omega$
		$V_{GS} = 4.0 \text{ V}$	$I_D = 8.5 \text{ A}^b$	-	-	0.27	
Forward Transconductance	$g_{fs}$	$V_{DS} = 50 \text{ V}$ , $I_D = 10 \text{ A}^b$		16	-	-	S
<b>Dynamic</b>							
Input Capacitance	$C_{iss}$	$V_{GS} = 0 \text{ V}$ , $V_{DS} = 25 \text{ V}$ $f = 1.0 \text{ MHz}$ , see fig. 5		-	1800	-	$\text{pF}$
Output Capacitance	$C_{oss}$			-	400	-	
Reverse Transfer Capacitance	$C_{rss}$			-	120	-	
Total Gate Charge	$Q_g$	$V_{GS} = 5.0 \text{ V}$	$I_D = 17 \text{ A}$ , $V_{DS} = 160 \text{ V}$ , see fig. 6 and 13 <sup>b</sup>	-	-	66	$\text{nC}$
Gate-Source Charge	$Q_{gs}$			-	-	9.0	
Gate-Drain Charge	$Q_{gd}$			-	-	38	
Turn-On Delay Time	$t_{d(on)}$			-	8.0	-	
Rise Time	$t_r$	$V_{DD} = 100 \text{ V}$ , $I_D = 17 \text{ A}$ $R_g = 4.6 \Omega$ , $R_D = 5.7 \Omega$ , see fig. 10 <sup>b</sup>		-	83	-	$\text{ns}$
Turn-Off Delay Time	$t_{d(off)}$		-	44	-		
Fall Time	$t_f$		-	52	-		
Internal Drain Inductance	$L_D$		-	4.5	-		
Internal Source Inductance	$L_S$	Between lead, 6 mm (0.25") from package and center of die contact		-	7.5	-	$\text{nH}$
Gate Input Resistance	$R_g$			$f = 1 \text{ MHz}$ , open drain	0.3	-	
<b>Drain-Source Body Diode Characteristics</b>							
Continuous Source-Drain Diode Current	$I_S$	MOSFET symbol showing the integral reverse p - n junction diode		-	-	17	$\text{A}$
Pulsed Diode Forward Current <sup>a</sup>	$I_{SM}$			-	-	68	
Body Diode Voltage	$V_{SD}$	$T_J = 25 \text{ }^{\circ}\text{C}$ , $I_S = 17 \text{ A}$ , $V_{GS} = 0 \text{ V}^b$		-	-	2.0	V
Body Diode Reverse Recovery Time	$t_{rr}$	$T_J = 25 \text{ }^{\circ}\text{C}$ , $I_F = 17 \text{ A}$ , $dI/dt = 100 \text{ A}/\mu\text{s}^b$		-	310	470	ns
Body Diode Reverse Recovery Charge	$Q_{rr}$			-	3.2	4.8	$\mu\text{C}$
Forward Turn-On Time	$t_{on}$	Intrinsic turn-on time is negligible (turn-on is dominated by $L_S$ and $L_D$ )					

**Notes**

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).  
b. Pulse width  $\leq 300 \mu\text{s}$ ; duty cycle  $\leq 2 \%$ .

**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)

**Fig. 1 - Typical Output Characteristics,  $T_c = 25 \text{ }^\circ\text{C}$** 

**Fig. 3 - Typical Transfer Characteristics**

**Fig. 2 - Typical Output Characteristics,  $T_c = 150 \text{ }^\circ\text{C}$** 

**Fig. 4 - Normalized On-Resistance vs. Temperature**

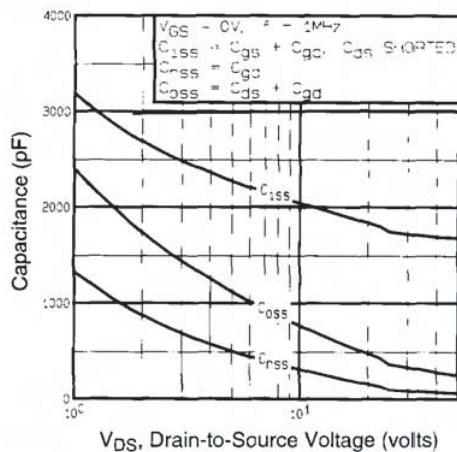


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

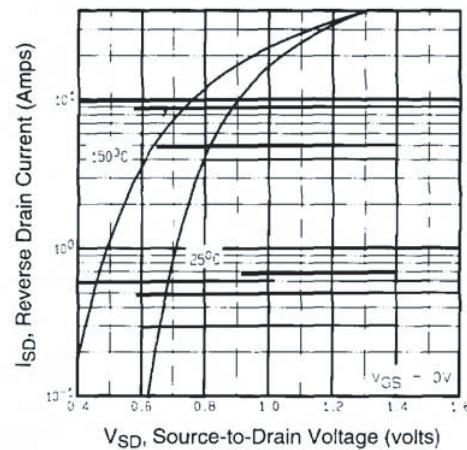


Fig. 7 - Typical Source-Drain Diode Forward Voltage

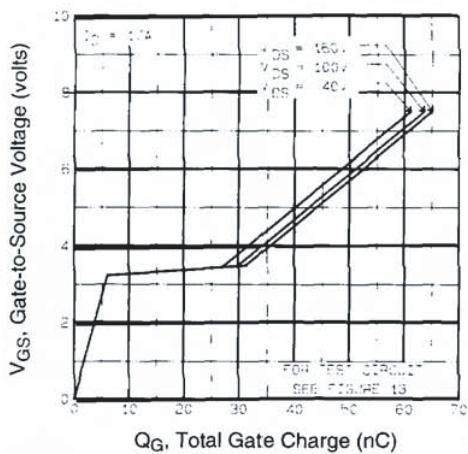


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

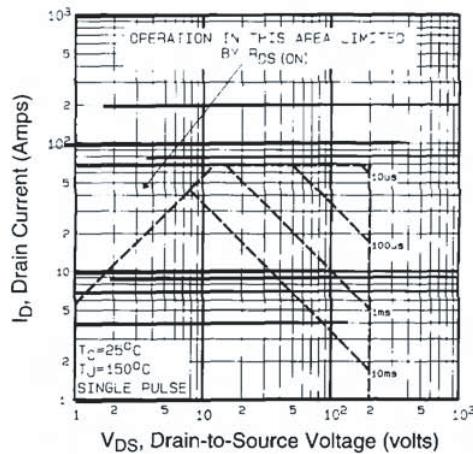


Fig. 8 - Maximum Safe Operating Area

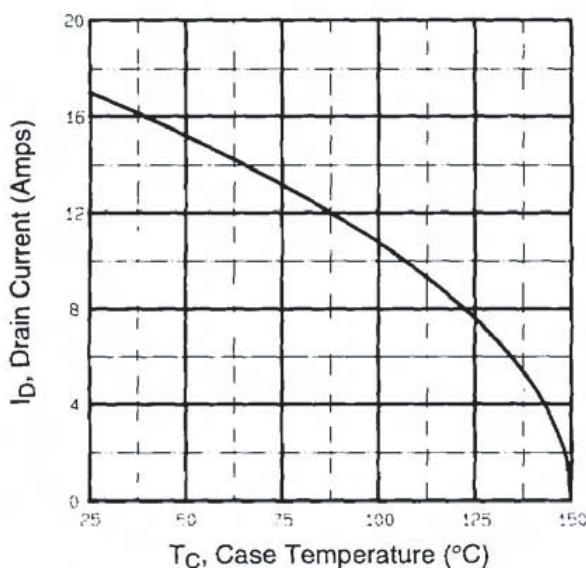


Fig. 9 - Maximum Drain Current vs. Case Temperature

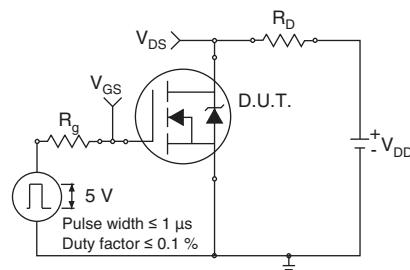


Fig. 10a - Switching Time Test Circuit

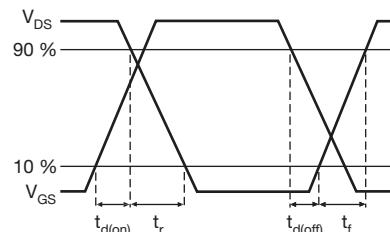


Fig. 10b - Switching Time Waveforms

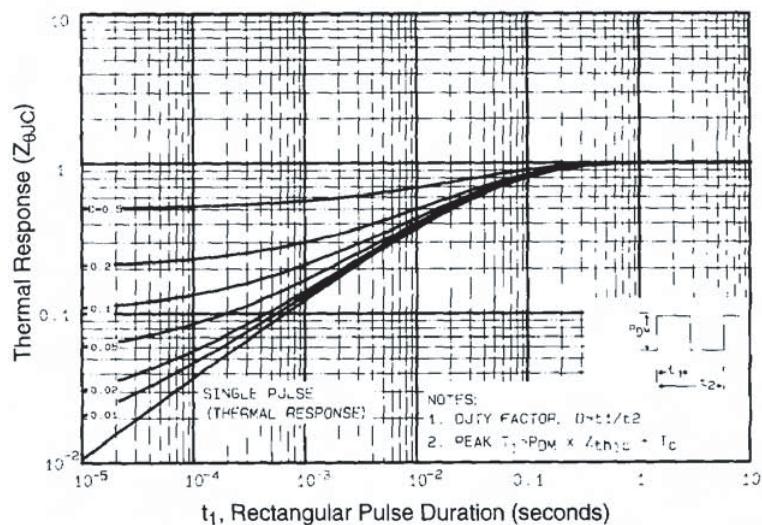


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

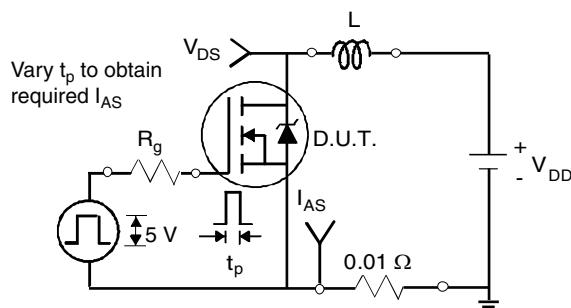


Fig. 12a - Unclamped Inductive Test Circuit

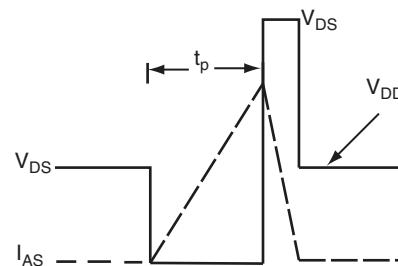


Fig. 12b - Unclamped Inductive Waveforms

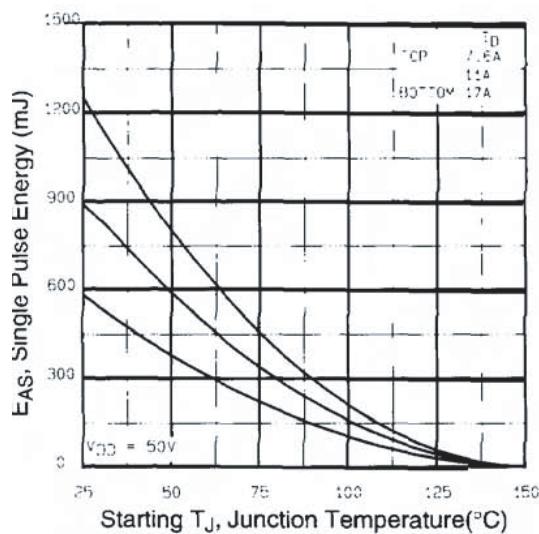


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

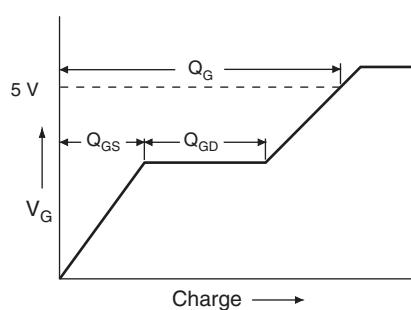


Fig. 13a - Basic Gate Charge Waveform

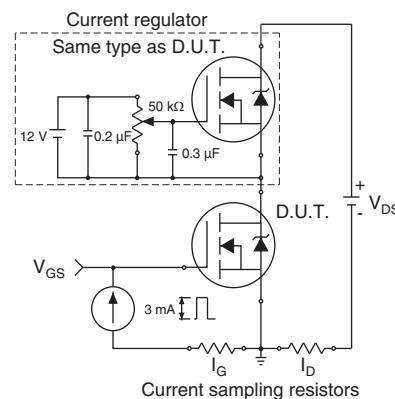
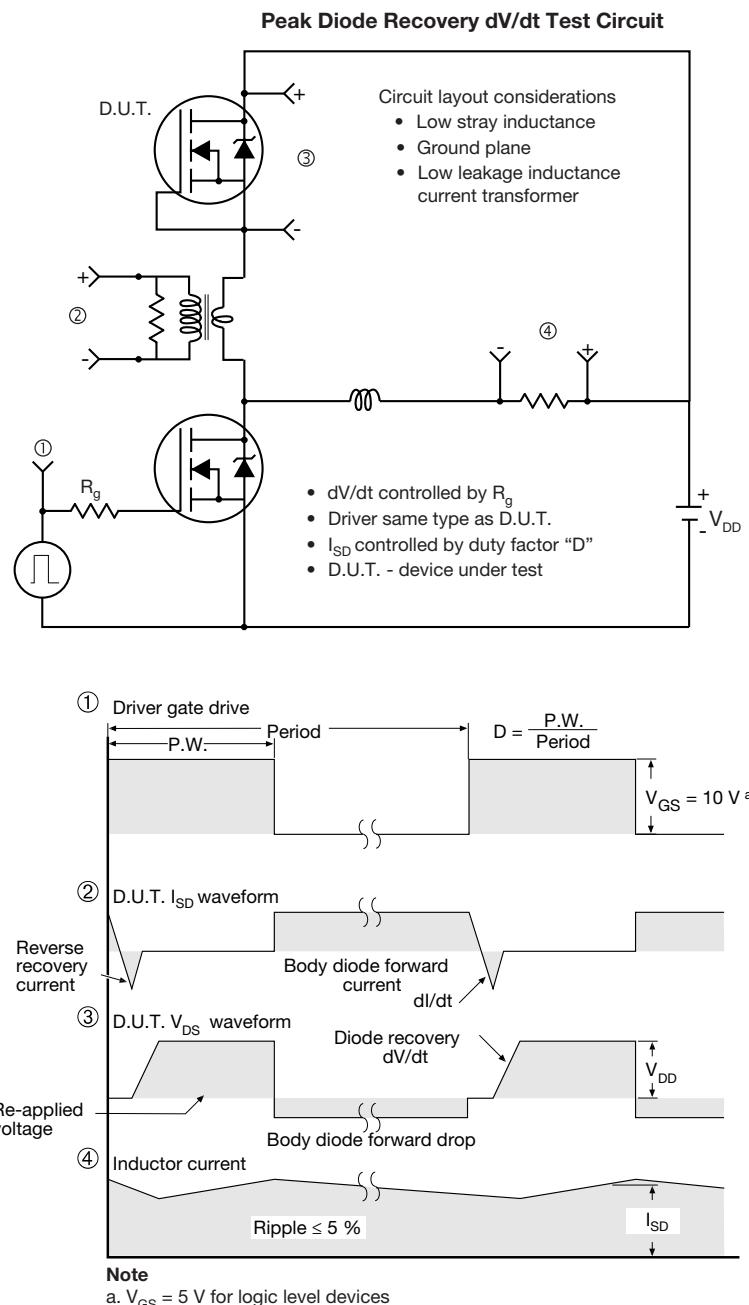
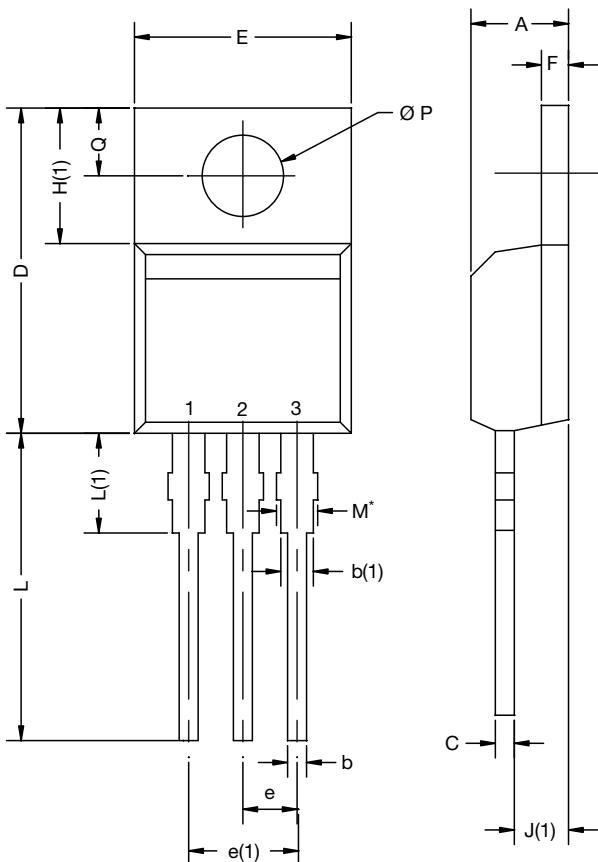


Fig. 13b - Gate Charge Test Circuit


**Fig. 14 - For N-Channel**

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TO-220-1



DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	4.24	4.65	0.167	0.183
b	0.69	1.02	0.027	0.040
b(1)	1.14	1.78	0.045	0.070
c	0.36	0.61	0.014	0.024
D	14.33	15.85	0.564	0.624
E	9.96	10.52	0.392	0.414
e	2.41	2.67	0.095	0.105
e(1)	4.88	5.28	0.192	0.208
F	1.14	1.40	0.045	0.055
H(1)	6.10	6.71	0.240	0.264
J(1)	2.41	2.92	0.095	0.115
L	13.36	14.40	0.526	0.567
L(1)	3.33	4.04	0.131	0.159
Ø P	3.53	3.94	0.139	0.155
Q	2.54	3.00	0.100	0.118

## Note

- $M^*$  = 0.052 inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM

## Package Picture

The image displays four physical packages of power MOSFETs arranged in a grid. The top row contains labels: 'Package Picture' at the top center, 'ASE' on the left of the first two columns, and 'Xi'an' on the right of the last two columns. The bottom row shows the physical components. From left to right: 1) An IRF9N60A MOSFET in a TO-220 package, showing a black plastic case with three metal pins extending downwards. 2) A bare metal heat spreader or substrate with a central circular hole and two rectangular cutouts, matching the footprint of the IRF9N60A. 3) An IRF9510 MOSFET in a TO-220 package, showing a black plastic case with three metal pins extending downwards. 4) A bare metal heat spreader or substrate with a central circular hole and two rectangular cutouts, matching the footprint of the IRF9510.



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